



STPS2H100A/U

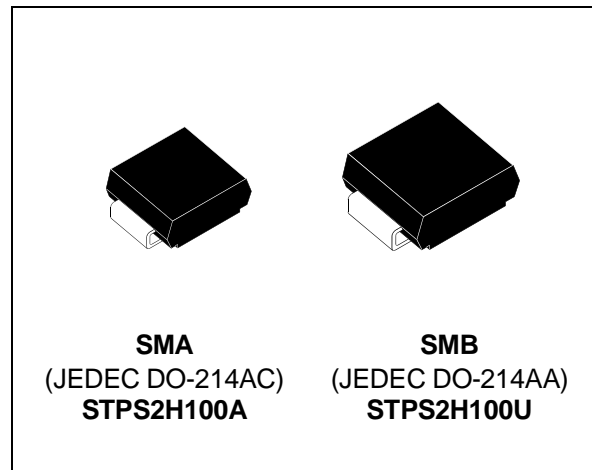
HIGH VOLTAGE POWER SCHOTTKY RECTIFIER

MAIN PRODUCT CHARACTERISTICS

$I_{F(AV)}$	2 A
V_{RRM}	100 V
T_j (max)	175 °C
V_F (max)	0.65 V

FEATURES AND BENEFITS

- NEGLIGIBLE SWITCHING LOSSES
- HIGH JUNCTION TEMPERATURE CAPABILITY
- LOW LEAKAGE CURRENT
- GOOD TRADE OFF BETWEEN LEAKAGE CURRENT AND FORWARD VOLTAGE DROP
- AVALANCHE RATED



DESCRIPTION

Schottky rectifier designed for high frequency miniature Switched Mode Power Supplies such as adaptators and on board DC/DC converters.

Packaged in SMA or SMB.

ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value	Unit
V_{RRM}	Repetitive peak reverse voltage	100	V
$I_{F(RMS)}$	RMS forward current	10	A
$I_{F(AV)}$	Average forward current	$T_L = 130^\circ\text{C } \delta = 0.5$ 2	A
I_{FSM}	Surge non repetitive forward current	$t_p = 10 \text{ ms sinusoidal}$ 75	A
I_{RRM}	Repetitive peak reverse current	$t_p = 2 \mu\text{s } F = 1\text{kHz square}$ 1	A
I_{RSM}	Non repetitive peak reverse current	$t_p = 100 \mu\text{s square}$ 1	A
T_{stg}	Storage temperature range	- 65 to + 175	°C
T_j	Maximum operating junction temperature	175	°C
dV/dt	Critical rate of rise of reverse voltage	10000	V/ μs

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THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
$R_{th(j-l)}$	Junction to lead	SMA	30
		SMB	25

STATIC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Tests conditions	Min.	Typ.	Max.	Unit	
I_R^*	Reverse leakage current	$T_j = 25^\circ\text{C}$	$V_R = V_{RRM}$		1	μA	
		$T_j = 125^\circ\text{C}$		0.4	1	mA	
V_F^{**}	Forward voltage drop	$T_j = 25^\circ\text{C}$	$I_F = 2\text{ A}$		0.79	V	
		$T_j = 125^\circ\text{C}$		0.6	0.65		
		$T_j = 25^\circ\text{C}$		$I_F = 4\text{ A}$			0.88
		$T_j = 125^\circ\text{C}$			0.69		0.74

Pulse test : * $t_p = 5\text{ ms}$, $\delta < 2\%$
 ** $t_p = 380\text{ }\mu\text{s}$, $\delta < 2\%$

To evaluate the maximum conduction losses use the following equation :
 $P = 0.56 I_{F(AV)} + 0.045 I_{F(RMS)}^2$

Fig. 1: Average forward power dissipation versus average forward current.

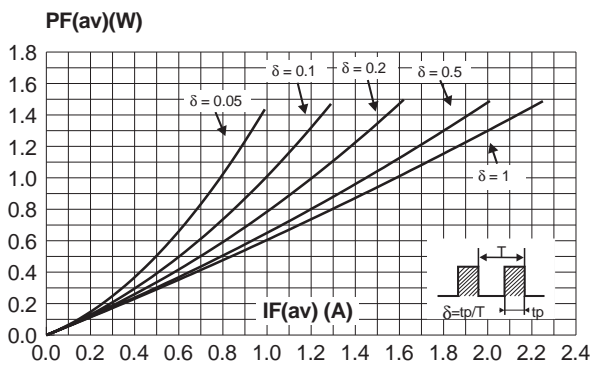


Fig. 2: Average forward current versus ambient temperature ($\delta=0.5$).

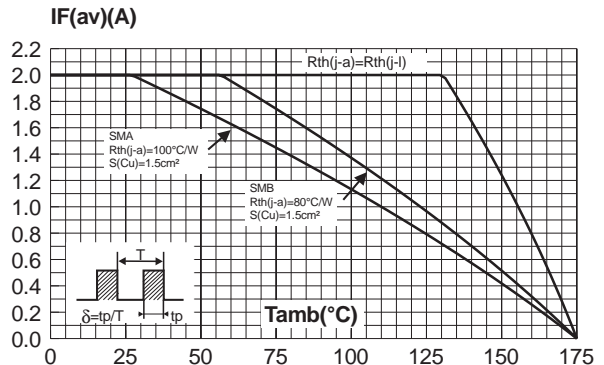


Fig. 3: Non repetitive surge peak forward current versus overload duration (maximum values) (SMB).

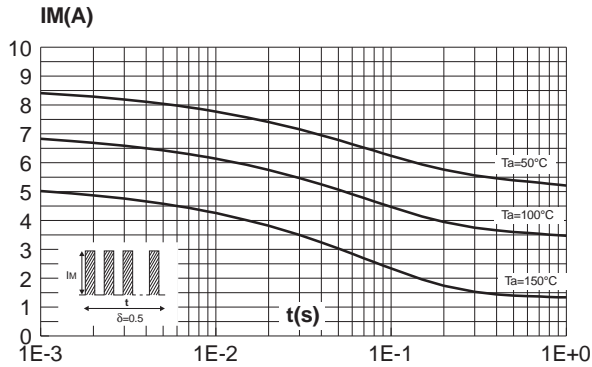


Fig. 4: Non repetitive surge peak forward current versus overload duration (maximum values) (SMA).

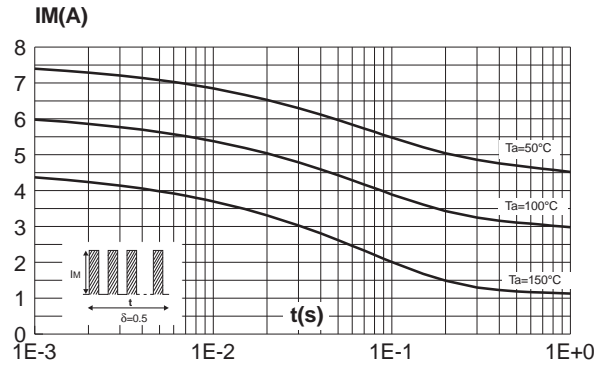


Fig. 5: Relative variation of thermal impedance junction to ambient versus pulse duration (SMB).

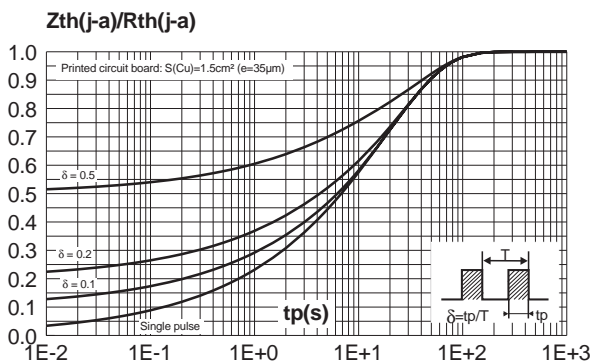


Fig. 6: Relative variation of thermal impedance junction to ambient versus pulse duration (SMA).

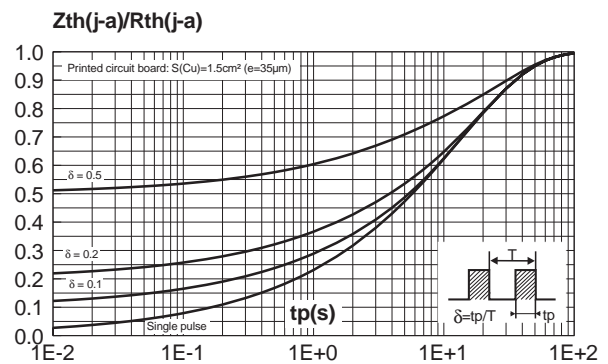


Fig. 7: Reverse leakage current versus reverse voltage applied (typical values).

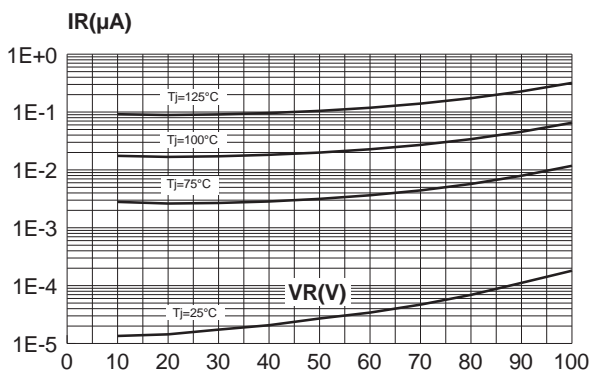
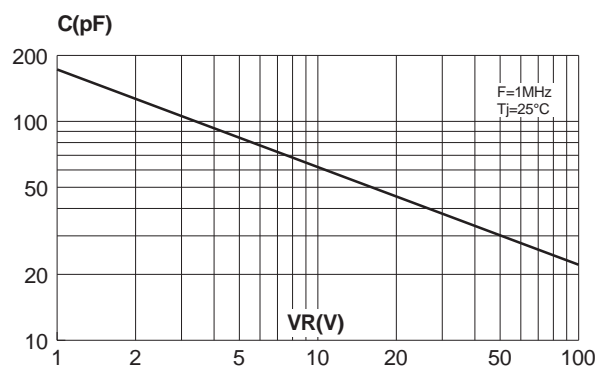


Fig. 8: Junction capacitance versus reverse voltage applied (typical values).



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Fig. 9: Thermal resistance junction to ambient versus copper surface under each lead (Epoxy printed circuit board FR4, copper thickness: 35 μ m) (SMB).

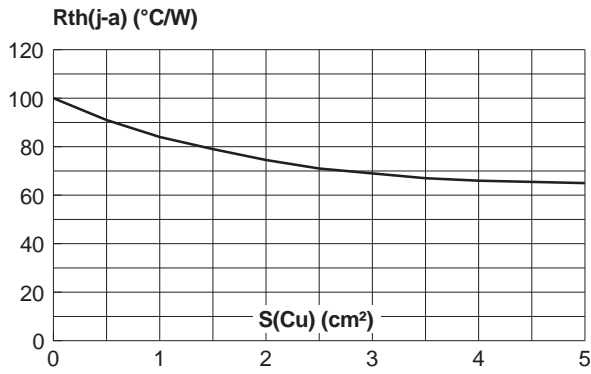


Fig. 10: Thermal resistance junction to ambient versus copper surface under each lead (Epoxy printed circuit board FR4, copper thickness: 35 μ m) (SMA).

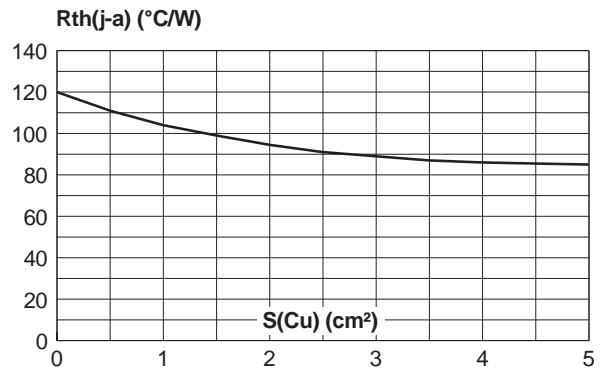
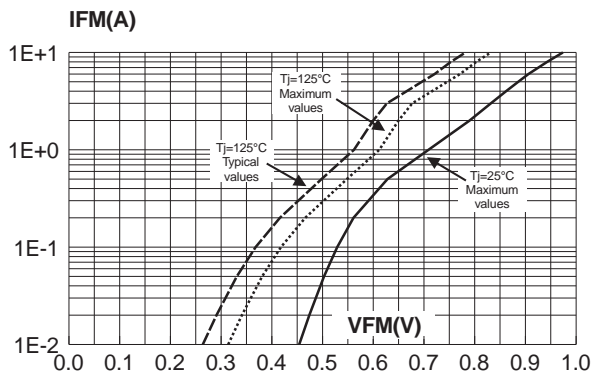
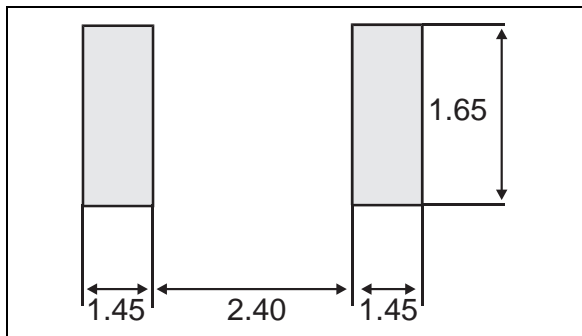


Fig. 11: Forward voltage drop versus forward current.



PACKAGE MECHANICAL DATA
 SMA

REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.70	0.075	0.106
A2	0.05	0.20	0.002	0.008
b	1.25	1.65	0.049	0.065
c	0.15	0.41	0.006	0.016
E	4.80	5.60	0.189	0.220
E1	3.95	4.60	0.156	0.181
D	2.25	2.95	0.089	0.116
L	0.75	1.60	0.030	0.063

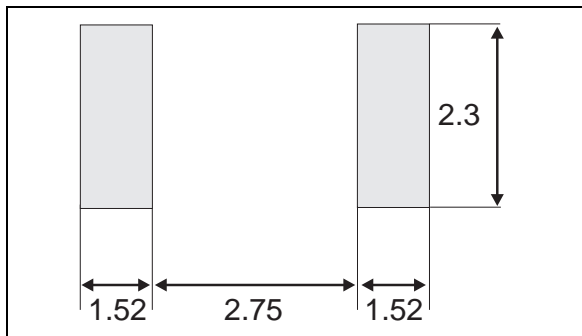
FOOT PRINT (in millimeters)


STPS2H100A/U

PACKAGE MECHANICAL DATA SMB

	DIMENSIONS				
	REF.	Millimeters		Inches	
		Min.	Max.	Min.	Max.
A1	1.90	2.45	0.075	0.096	
A2	0.05	0.20	0.002	0.008	
b	1.95	2.20	0.077	0.087	
c	0.15	0.41	0.006	0.016	
E	5.10	5.60	0.201	0.220	
E1	4.05	4.60	0.159	0.181	
D	3.30	3.95	0.130	0.156	
L	0.75	1.60	0.030	0.063	

FOOT PRINT (in millimeters)



Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STPS2H100A	S21	SMA	0.068g	5000	Tape & reel
STPS2H100U	G21	SMB	0.107g	2500	Tape & reel

- Band indicates cathode
- Epoxy meets UL94, V0

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